## Dual 4x4 Low Resistance Analog Switch Array Chip CH449

Datasheet<br>Version: 1A<br>http://wch.cn

## 1. Overview

CH449 is a $4 \times 4$ matrix differential signal analog switch chip. CH449 contains 32 analog switches, which are divided into two groups and distributed at each cross-point of dual $4 \times 4$ signal channel matrices. Each analog switch can be turned on/off independently, so as to implement any dynamic connection of 4 x 4 differential signal channels.

CH449 supports 5 V rated supply voltage, with high bandwidth and low ON resistance, and supports 3.3 V or lower supply voltage, can be used for dynamic switch and combination switch between four inputs and four outputs of video or USB2.0 differential signals. For USB3.0, DP1.4 and 5Gbps differential signal matrix analog switch, please refer to CH9444/CH9445 datasheet.

The CH449 series includes CH449F and CH449X. CH449F uses NMOS and PMOS to implement analog switch, and supports the rail-to-rail full-amplitude analog signal. CH449X uses NMOS to implement analog switch, with higher bandwidth, and only supports analog signals with voltage lower than VDD-1.4V. When CH449X is used for signal switch, it can prevent the current from flowing back to VDD by external electrical signals after power down.


## 2. Features

- A dual $4 \times 4$ cross-point matrix analog switch, supports four-in four-out differential signal switch.
- Supports switch of two groups of independent four-in four-out single-ended signals.
- Low ON resistance, Ron typical value of about $5 \Omega$.

High bandwidth. Supports video signal, low-speed, full-speed and high-speed USB signals.

- 2KV HBM ESD.
- Compatible with IIC two-wire serial control interface. 2 sets of device addresses for selection.
- Built-in power on reset and low voltage reset. Supports external input reset.
- The voltage of all control signals is independent of the supply voltage. Supports $5 \mathrm{~V}, 3.3 \mathrm{~V}, 2.5 \mathrm{~V}$ and 1.8 V control signals.
- Wide supply voltage range. Low static power dissipation. Supports 5 V rated supply voltage, power supply can be down to 2.5 V .
- Package: QFN24, compatible with RoHS.


## 3. Package

| Package | Body size |  | Lead pitch |  | Description | Part No. |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| QFN24 | $4 * 4 \mathrm{~mm}$ |  | 0.50 mm | 19.7 mil | Quad no-lead 24-pin | CH449F |
| QFN24 | $4 * 4 \mathrm{~mm}$ |  | 0.50 mm | 19.7 mil | Quad no-lead 24-pin | CH449X |

Note: For QFN package, the EPAD is marked as 0\# pin, which is unnecessary but recommended to connect.


## 4. Pin definitions

| Pin No. | Pin Name | Pin Type | Description |
| :---: | :---: | :---: | :---: |
| 2 | VDD | Power | Positive power |
| 13,0 | GND | Power | Ground, digital signal reference ground |
| 24 | SCL | Input | Clock input of 2-wire serial interface |
| 23 | SDA | Input and <br> open-drain <br> output | Data input and response output of 2-wire serial interface <br> Built-in controllable pull-up resistor |
| 1 | PU_SDA | Input | 2-wire serial interface SDA pull-up resistor enable: <br> Low level - built-in resistor disabled; <br> High level - built-in resistor enabled. |
| 11 | ADDR | Input | Device address selection input of 2-wire serial interface |
| 12 | RSTI\# | Input | External reset input, active low |
| 14 | LVR\# | Open-drain <br> output | Internal low voltage reset output, active low, used for low <br> voltage monitor |
| 4,3 | A0X, A0Y | Analog signal | Terminal 0\# of analog switch array port A |


| 6,5 | A1X, A1Y | Analog signal | Terminal 1\# of analog switch array port A |
| :---: | :---: | :--- | :--- |
| 8,7 | A2X, A2Y | Analog signal | Terminal 2\# of analog switch array port A |
| 10,9 | A3X, A3Y | Analog signal | Terminal 3\# of analog switch array port A |
| 22,21 | B0X, B0Y | Analog signal | Terminal 0\# of analog switch array port B |
| 20,19 | B1X, B1Y | Analog signal | Terminal 1\# of analog switch array port B |
| 18,17 | B2X, B2Y | Analog signal | Terminal 2\# of analog switch array port B |
| 16,15 | B3X, B3Y | Analog signal | Terminal 3\# of analog switch array port B |

## 5. Functional specification

### 5.1. Analog switch array

The $4 \times 4$ differential matrix switch of CH 449 includes two completely independent analog switch arrays X and Y. Each switch array has four ports A and four ports B. Each cross-point of $4 * 4$ matrix has an analog switch. The S0X-S15X codes are used for the channel X, and the S0Y-S15Y codes are used for the channel Y. These analog switches are OFF by default after reset, and combinations can be set to ON/OFF by the external MCU through a 2-wire control interface.

Analog switch codes for the channel X:

| X matrix | B0X pin | B1X pin | B2X pin | B3X pin |
| :---: | :---: | :---: | :---: | :---: |
| A0X pin | S0X | S1X | S2X | S3X |
| A1X pin | S4X | S5X | S6X | S7X |
| A2X pin | S8X | S9X | S10X | S11X |
| A3X pin | S12X | S13X | S14X | S15X |

Analog switch codes for the channel Y:

| Y matrix | B0Y pin | B1Y pin | B2Y pin | B3Y pin |
| :---: | :---: | :---: | :---: | :---: |
| A0Y pin | S0Y | S1Y | S2Y | S3Y |
| A1Y pin | S4Y | S5Y | S6Y | S7Y |
| A2Y pin | S8Y | S9Y | S10Y | S11Y |
| A3Y pin | S12Y | S13Y | S14Y | S15Y |

### 5.2. Two-wire serial control interface

The two-wire serial interface implements transfer through SCL and SDA signal lines. SCL is a clock line, and SDA is a serial data line. Always MSB-first for serial data shift. A complete control command consists of a command and 16-bit data (including start bit, device address and command byte, response 1, high 8-bit switch data, response 2 , low 8 -bit switch data, response 3 and stop bit).
The lowest bit of device address and command byte is the command bit. CH449 only supports the operation with command bit of 0 . The high 7 bits are the 7 -bit device address selected by ADDR pin, which cannot be suspended.

When ADDR pin is at low level, the address ranges from $0 \times 19$ to $0 \times 1 \mathrm{~B}$, the device address and command byte are $0 \times 3 \mathrm{X}$. When ADDR pin is at high level, the address ranges from $0 \times 29$ to $0 \times 2 \mathrm{~B}$, and the device address and command byte are $0 \times 5 \mathrm{X}$.

|  | Bit 7 | Bit 6 | Bit 5 | Bit 4 | Bit 3 | Bit 2 | Bit 1 | Bit 0 | Description |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Format | 0 | ADDR | !ADDR | 1 | 0 | YE | XE | 0 | !ADDR refers to the inverse of <br> the ADDR state |
| Example 1 | 0 | ADDR | $!$ ADDR | 1 | 0 | 0 | 1 | 0 | Set S15X $\sim$ S0X of channel X |


| Example 2 | 0 | ADDR | !ADDR | 1 | 0 | 1 | 0 | 0 | Set S15Y ~S0Y of channel Y |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Example 3 | 0 | ADDR | !ADDR | 1 | 0 | 1 | 1 | 0 | Simultaneously set S15 $\sim$ S0 of <br> channels X and Y |

The high 8-bit switch data and the low 8-bit switch data constitute the 16-bit switch data. CH449 confirms to save the 16 -bit data and apply it to the channel $\mathrm{X}+\mathrm{Y}$ or X or Y according to the device address and $\mathrm{XE} / \mathrm{YE}$ in the command byte. When the data bit is 1 , the corresponding analog switch is on. When the data bit is 0 , the corresponding analog switch is off. The switches can be combined in any way, but need to avoid short circuits between several signal sources. For example, A0 and A2 are on when S0, S3 and S11 are 1, A0 and B 0 are on, A 0 and B 3 are on, A 2 and B 3 are on.

|  | Bit 7 | Bit 6 | Bit 5 | Bit 4 | Bit 3 | Bit 2 | Bit 1 | Bit 0 | Description |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| High 8-bit data | S15 | S14 | S13 | S12 | S11 | S10 | S9 | S8 | Each bit corresponds to a switch of the matrix cross-point, and can be combined in any way |
| Low 8-bit data | S7 | S6 | S5 | S4 | S3 | S2 | S1 | S0 |  |

In the differential signal switch matrix application, the channels X and Y should be set uniformly, and the differential signals $X$ and $Y$ can be set to $+/-(\mathrm{p} / \mathrm{n})$ or the inverse according to PCB design optimization requirements.

The PU_SDA pin is used to enable the built-in SDA pull-up resistor of CH449. In the application of MCU with built-in pull-up resistor or external pull-up resistor, PU_SDA should be shorted to GND, to disable the built-in pull-up resistor. The PU_SDA pin cannot be suspended.

### 5.3. Power and reset

CH449 digital pins include SCL, SDA, ADDR, PU_SDA, RSTI\#, and LVR\#. These pins support 5V-tolerant, and the input voltage can be independent of CH449 supply voltage (VDD).

ADDR is usually connected to GND or VDD as required, and PU_SDA is usually connected to GND or VDD as required.

SCL and SDA are usually driven by the I/O of the external MCU, and CH449 allows the MCU to use a supply voltage which is different from the supply voltage of CH 449 .

| Combinations of CH449 supply voltage <br> and digital pin control voltage | CH449 supply voltage (VDD), maximum voltage <br> of analog signal |  |  |  |
| :---: | :---: | :---: | :---: | :---: |
|  | 5 V | 5 V | 3.3 V | 2.5 V |
| I/O voltage of MCU <br> (Voltage on CH449 <br> digital input pins) | 3.3 V | Function <br> support | $\sqrt{ }$ | $\sqrt{ }$ |
|  | 2.5 V | Function <br> support | Function <br> support | $\sqrt{ }$ |
|  | 1.8 V | $\times$ | Function <br> support | Function <br> support |

Note: "Function support" in the table above means that the function can be implemented completely, but CH449 may have a static power dissipation of not more than 400 uA .

The RSTI\# pin is used to input the external reset signal, active low. All analog switches will be turned off after reset. It can be connected to VDD when the external reset input is not required. The RSTI\# pin cannot be suspended.

During I/O switch in a dual power system, RSTI\# can be connected to power supply of the other party, to automatically reset CH 449 when its own power is on but the other party is powered off, so as to turn off all analog switches and all I/Os. If CH449X is used, it can prevent the current from back flowing to VDD through PMOS analog switch when its own power is off but the other party is powered on.

In the application of MCU I/O with only 3.3 V supply voltage but 5 V external signal voltage, CH 449 X can also be connected to I/O link in series after supplied by 5 V power, so that it has the voltage withstand capacity to the external 5 V signal. The voltage of 5 V signal is decreased to below 3.6 V by CH 449 X with 5 V power supply, and the voltage of 3.3 V signal is decreased to below 2.2 V by CH 449 X with 3.3 V power supply.

The LVR\# pin is the internal low voltage reset output, active low. LVR\# outputs low level when VDD supply voltage is lower than VR. It can also be shorted to VCC, to discharge VDD when VDD power is off or when at low voltage.

## 6. Parameters

### 6.1. Absolute maximum ratings

Stresses at or above the absolute maximum ratings listed in the table below may cause permanent damage to the device.

| Symbol | Parameter description | Min. | Max. | Unit |
| :---: | :---: | :---: | :---: | :---: |
| TA | Operating ambient temperature | -40 | 85 | ${ }^{\circ} \mathrm{C}$ |
| TS | Storage ambient temperature | -55 | 125 | ${ }^{\circ} \mathrm{C}$ |
| VDD | Supply voltage (VDD connects to power, GND connects to ground) | -0.5 | 6.5 | V |
| VANA | Voltage on analog input/output pins of CH449F | -0.5 | VDD +0.4 | V |
| VANAN | Voltage on analog input/output pins of CH449X (not related to VDD) | -0.5 | 6.5 | V |
| VIOD | Voltage on digital input/output pins (not related to VDD) | -0.5 | 6.5 | V |
| Isw | Continuous through current of analog switch | 0 | 30 | mA |
| Iall | Total continuous through current of all analog switches | 0 | 120 | mA |

### 6.2. Electrical characteristics at 5 V

Test conditions: $\mathrm{TA}=25^{\circ} \mathrm{C}, \mathrm{VDD}=5 \mathrm{~V}$

| Symbol | Parameter description | Min. | Typ. | Max. | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: |
| VDD | Supply voltage | 4.0 | 5.0 | 5.5 | V |
| ICC | Static supply current, with all digital pins <br> connected to VDD or GND |  | 2 | 10 | uA |
| ICCX | Static supply current, with all digital pins at <br> $1.8 V$ |  | 0.5 | 2 | mA |
| VIL | Low level input voltage of digital pins | 0 |  | 1.1 | V |
| VIH | High level input voltage of digital pins | 2.2 | 5.5 | V |  |
| ILEAK | Input leakage current of digital pins |  | 0.1 | 10 | uA |
| IUSDA | Pull-up current of SDA pin with internal <br> resistor enabled | 250 | 500 | 700 | uA |
| ILSDA | Low level absorption current of SDA pin <br> $@$ @DA=0.5V | 4 | 5.5 | mA |  |


| VR | Default power on reset threshold | 1.8 | 2 | 2.2 | V |
| :---: | :---: | :---: | :---: | :---: | :---: |
| ILVR | Absorption current of LVR\# pin during reset (shorted to VDD) | 0 | 21 | 55 | mA |
| IOFF | Leakage current of analog switch in off state |  | $\pm 0.05$ | $\pm 1$ | uA |
| VANA | Recommended voltage range of analog signal | 0 |  | 2.8 | V |
| VANAX | Allowed voltage range of analog signal of CH449F | -0.3 |  | VDD +0.3 | V |
| VANAN | Allowed voltage range of analog signal of CH449X | -0.3 | <VDD-1.8 | VDD-1.4 | V |
| RON1 | Analog switch ON resistance, with analog signal voltage of 0 V |  | 4 | 7 | $\Omega$ |
| RON2 | Analog switch ON resistance, with analog signal voltage of 2 V |  | 6 | 10 | $\Omega$ |
| RON3 | CH449F switch ON resistance, with signal voltage of 3.4 V |  | 10 | 15 | $\Omega$ |
| RON4 | CH449F switch ON resistance, with signal voltage of 5 V |  | 6 | 10 | $\Omega$ |
| RON5 | CH449X switch ON resistance, with signal voltage of 3.2 V |  | 80 | 120 | $\Omega$ |
| RON6 | CH449X switch ON resistance, with signal voltage of 3.5 V |  | 5K |  | $\Omega$ |

### 6.3. Electrical characteristics at 3.3 V

Test conditions: $\mathrm{TA}=25^{\circ} \mathrm{C}, \mathrm{VDD}=3.3 \mathrm{~V}$

| Symbol | Parameter description | Min. | Typ. | Max. | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: |
| VDD3 | Supply voltage | 2.1 | 3.3 | 3.9 | V |
| ICC3 | Static supply current, with all digital pins <br> connected to VDD or GND |  | 1 | 5 | uA |
| ICCX3 | Static supply current, with all digital pins at <br> 1.3 V |  | 0.2 | 1 | mA |
| VIL3 | Low level input voltage of digital pins | 0 |  | 0.7 | V |
| VIH3 | High level input voltage of digital pins | 1.8 |  | 5.5 | V |
| ILEAK3 | Input leakage current of digital pins |  | 0.1 | 5 | uA |
| IUSDA3 | Pull-up current of SDA pin with internal <br> resistor enabled | 100 | 210 | 300 | uA |
| ILSDA3 | Low level absorption current of SDA pin <br> @SDA=0.5V | 2.5 | 3.8 | mA |  |
| VR | Default power on reset threshold | 1.8 | 2 | 2.2 | V |
| ILVR3 | Absorption current of LVR\# pin during reset <br> (shorted to VDD) | 0 | 21 | 40 | mA |
| IOFF3 | Leakage current of analog switch in off state |  | $\pm 0.02$ | $\pm 0.5$ | uA |
| VANA3 | Recommended voltage range of analog signal | 0 |  | 1.5 | V |
| VANAX3 | Allowed voltage range of analog signal of <br> CH449F | -0.3 |  | VDD3+0.3 | V |
| VANAN3 | Allowed voltage range of analog signal of <br> CH449X | -0.3 | $<$ VDD3-1.5 | VDD3-1.1 | V |


| RON1 | Analog switch ON resistance, with analog <br> signal voltage of 0V | 5 | 9 | $\Omega$ |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
| RON2 | Analog switch ON resistance, with analog <br> signal voltage of 1.2V |  | 10 | 14 | $\Omega$ |
| RON3 | CH449F switch ON resistance, with signal <br> voltage of 2.0V | 20 | 28 | $\Omega$ |  |
| RON4 | CH449F switch ON resistance, with signal <br> voltage of 3.3V |  | 8 | 12 | $\Omega$ |
| RON5 | CH449X switch ON resistance, with signal <br> voltage of 1.8V | 45 | 70 | $\Omega$ |  |
| RON6 | CH449X switch ON resistance, with signal <br> voltage of 2.1V |  | 4 K |  | $\Omega$ |

### 6.4. Interface timing parameters

Test conditions: $\mathrm{TA}=25^{\circ} \mathrm{C}, \mathrm{VDD}=5 \mathrm{~V}$ or $\mathrm{VDD}=3.3 \mathrm{~V}$, Refer to the attached figure

| Symbol | Parameter description | Min. | Typ. | Max. | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: |
| TSSTA | Setup time of SDA falling edge start signal | 100 |  |  | nS |
| THSTA | Hold time of SDA falling edge start signal | 100 |  |  | nS |
| TSSTO | Setup time of SDA rising edge stop signal | 100 |  |  | nS |
| THSTO | Hold time of SDA rising edge stop signal | 100 |  | nS |  |
| TCLOW | Low level width of SCL clock signal | 100 |  | nS |  |
| TCHIG | High level width of SCL clock signal | 100 |  | nS |  |
| TSDA | Setup time of SDA input data to SCL rising <br> edge | 30 |  | 40 | nS |
| THDA | Hold time of SDA input data to SCL rising <br> edge | 20 |  | 60 | nS |
| TAA | Delay of SDA output data valid to SCL <br> falling edge | 5 |  | 2 M | bps |
| TDH | Delay of SDA output data invalid to SCL <br> falling edge | 5 |  |  |  |
| Rate | Average data transfer rate | 0 |  |  |  |



### 6.5. Other timing parameters

Test conditions: $\mathrm{TA}=25^{\circ} \mathrm{C}, \mathrm{VDD}=5 \mathrm{~V}$, VANA $=0 \mathrm{~V}, \mathrm{~F}=1 \mathrm{MHz}$ )

| Symbol | Parameter description | Min. | Typ. | Max. | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: |
| CIN | Digital input pin capacitance |  | 3 | 8 | pF |
| COFF | Analog signal pin capacitance when CH449F <br> switch is off |  | 7 | 10 | pF |
| CON | Analog signal pin capacitance when CH449F <br> switch is on |  | 10 | 15 | pF |
| BW | CH449F analog switch -3dB bandwidth | 350 | 500 |  | MHz |
| COFFN | Analog signal pin capacitance when CH449X <br> switch is off |  | 4 | 7 | pF |
| CONN | Analog signal pin capacitance when CH449X <br> switch is on |  | 6 | 11 | pF |
| BWN | CH449X analog switch -3dB bandwidth | 500 | 800 |  | MHz |

### 6.6. Characteristic diagram

6.6.1 Correlation between CH 449 F analog switch ON resistance RON and analog signal voltage $\operatorname{VCOM}\left(\mathrm{TA}=25^{\circ} \mathrm{C}\right)$


## 7. Applications

### 7.1. Switch of several video signals

The CH449 features high bandwidth and low resistance, more suitable for video signal switch, such as selection from several video sources.

As the analog circuit and the digital circuit share VDD and GND, the GND pin must be in good connection, to reduce interference. The VDD pin must connected to an external decoupling capacitor. It is recommended to appropriately reduce the edge angle of the digital input signal, to reduce transfer frequency.

### 7.2. Switch of several USB signals

The CH449 supports dynamic reconstruction of 4-channel low-speed, full-speed and high-speed USB signal connections, to implement physical layer routing. If CH 449 X is selected, VDD should be 5 V . For matrix switch of SuperSpeed USB3.1 and DP1.4 signals, please refer to CH9444/CH9445 datasheet.

### 7.3. Digital I/O physical layer routing and I/O expansion

The CH449 can be used for digital signal routing between MCU and external I/O devices, and I/O connection can be dynamically reconstructed to implement function switch.

When MCU I/O is not enough, CH449 can be used to expand the low-speed output port (connected to external GND or VDD).

## 8. Package information

Note: All dimensions are in millimeters. The pin center spacing values are nominal values, and the error of other dimensions is not more than $\pm 0.2 \mathrm{~mm}$.

QFN24-4*4


